



# SLOVENSKI STANDARD

## SIST EN 62228-2:2017

01-april-2017

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**Integrirana vezja - Ocenjevanje elektromagnetne združljivosti (EMC) oddajnikov-sprejemnikov - 2. del: Oddajniki-sprejemniki za krajevno medvezalno omrežje (IEC 62228-2:2016)**

Integrated circuit - EMC Evaluation of transceivers - Part 2: LIN transceivers (IEC 62228-2:2016)

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Circuits intégrés - Évaluation de la CEM des émetteurs-récepteurs - Partie 2: Emetteurs-récepteurs LIN (IEC 62228-2:2016) [SIST EN 62228-2:2017](#)

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**Ta slovenski standard je istoveten z: EN 62228-2:2017**

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31.200	Integrirana vezja, mikroelektronika	Integrated circuits. Microelectronics
33.100.01	Elektromagnetna združljivost na splošno	Electromagnetic compatibility in general

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**en**

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EUROPEAN STANDARD

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February 2017

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Integrated circuits - EMC evaluation of transceivers -  
Part 2: LIN transceivers  
(IEC 62228-2:2016)

Circuits intégrés - Évaluation de la CEM des émetteurs-  
récepteurs - Partie 2: Émetteurs-récepteurs LIN  
(IEC 62228-2:2016)

Integrierte Schaltungen - Bewertung der  
elektromagnetischen Verträglichkeit von Sende-  
Empfangsgeräten - Teil 2: LIN-Sende-Empfangsgeräte  
(IEC 62228-2:2016)

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SIST EN 62228-2:2017

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Comité Européen de Normalisation Electrotechnique  
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels

**EN 62228-2:2017****European foreword**

The text of document 47A/994/FDIS, future edition 1 of IEC 62228-2, prepared by SC 47A "Integrated circuits" of IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 62228-2:2017.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2017-09-23
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2019-12-23

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## Annex ZA (normative)

### Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: [www.cenelec.eu](http://www.cenelec.eu)

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61967-1	-	Integrated circuits - Measurement of electromagnetic emissions, 150 kHz to 1 GHz - Part 1: General conditions and definitions	EN 61967-1	-
IEC 61967-4	-	Integrated circuits - Measurement of electromagnetic emissions, 150 kHz to 1 GHz - Part 4: Measurement of conducted emissions - 1 ohm/150 ohm direct coupling method	EN 61967-4	-
IEC 62132-1	-	Integrated circuits - Measurement of electromagnetic immunity - Part 1: General conditions and definitions	EN 62132-1	-
IEC 62132-4	-	Integrated circuits - Measurement of electromagnetic immunity, 150 kHz to 1 GHz - Part 4: Direct RF power injection method	EN 62132-4	-
IEC 62215-3	-	Integrated circuits - Measurement of impulse immunity - Part 3: Non-synchronous transient injection method	EN 62215-3	-
ISO 7637-2	-	Road vehicles - Electrical disturbances from conduction and coupling - Part-2: Electrical transient conduction along supply lines only	-	-
ISO 10605	-	Road vehicles - Test methods for electrical - disturbances from electrostatic discharge	-	-
ISO 17987-6	-	Road vehicles - Local Interconnect Network (LIN) - Part 6: Protocol conformance test specification	-	-

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# INTERNATIONAL STANDARD

# NORME INTERNATIONALE



Integrated circuits – EMC evaluation of transceivers –  
Part 2: LIN transceivers (standards.iteh.ai)

Circuits intégrés – Évaluation de la CEM des émetteurs-récepteurs –  
Partie 2: Émetteurs-récepteurs LIN

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## INTERNATIONAL ELECTROTECHNICAL COMMISSION

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**INTEGRATED CIRCUITS –  
EMC EVALUATION OF TRANSCEIVERS –**
**Part 2: LIN transceivers****FOREWORD**

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International Standard IEC 62228-2 has been prepared by subcommittee 47A: Integrated circuits, of IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
47A/994/FDIS	47A/998/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62228 series, published under the general title *Integrated circuits – EMC evaluation of transceivers*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

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# INTEGRATED CIRCUITS – EMC EVALUATION OF TRANSCEIVERS –

## Part 2: LIN transceivers

### 1 Scope

This part of IEC 62228 specifies test and measurement methods for EMC evaluation of LIN transceiver ICs under network condition. It defines test configurations, test conditions, test signals, failure criteria, test procedures, test setups and test boards. It is applicable for standard LIN transceiver ICs and ICs with embedded LIN transceiver and covers

- the emission of RF disturbances,
- the immunity against RF disturbances,
- the immunity against impulses and
- the immunity against electrostatic discharges (ESD).

### 2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

SIST EN 62228-2:2017

IEC 61967-1, *Integrated circuits – Measurement of electromagnetic emissions 150 kHz to 1 GHz – Part 1: General conditions and definitions*

IEC 61967-4, *Integrated circuits – Measurement of electromagnetic emissions 150 kHz to 1 GHz – Part 4: Measurement of conducted emissions – 1  $\Omega$  /150  $\Omega$  direct coupling method*

IEC 62132-1, *Integrated circuits – Measurement of electromagnetic immunity – Part 1: General conditions and definitions*

IEC 62132-4, *Integrated circuits – Measurement of electromagnetic immunity 150 kHz to 1 GHz – Part 4: Direct RF power injection method*

IEC 62215-3, *Integrated circuits – Measurement of impulse immunity – Part 3: Non-synchronous transient injection method*

ISO 7637-2, *Road vehicles — Electrical disturbances from conduction and coupling – Part 2: Electrical transient conduction along supply lines only*

ISO 10605, *Road vehicles – Test methods for electrical disturbances from electrostatic discharge*

ISO 17987-6.2<sup>1</sup>, *Road vehicles – Local interconnect network (LIN) – Part 6: Protocol conformance test specification*

<sup>1</sup> To be published.